

REDUCING OUTGASSING OF REACTIVE MATERIAL
UPON EXPOSURE OF PHOTOLITHOGRAPHY RESISTS

Abstract of the Disclosure

Outgassing of reactive material upon exposure of a photolithographic resist may be reduced. Outgassing may foul optical components of the photolithographic system.

5 In one embodiment, a ring compound with iodine or sulfur may be formed. The ring compound may be more resistant to the generation of reactive outgassing components.